

# 型号：3EC-M2S-VLP

- VLP™系列为低粗糙度的铜箔适用于减成法中的精细线路蚀刻。  
VLP™ series as low profile copper foil is suitable for fine-pattern etching in the subtractive process.
- VLP™系列具有高抗拉强度，易于薄型铜箔操作。  
High tensile strength, easy to handle thin foil.
- 具备薄至7 μm铜箔的量产能力。  
We can produce even 7um foil.

## 用途/Application

- 半导体封装基板  
/Semiconductor Package

## 构成/Composition



## 生产地点/Production Site

- 日本 / Japan

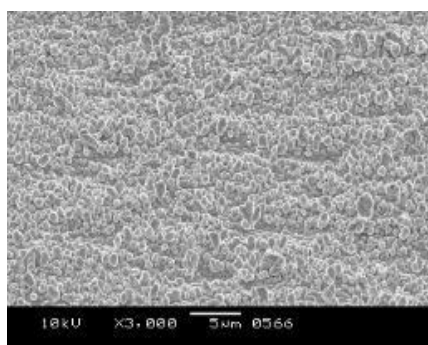
## 代表性特性数据/Representative data

Model No.	μm	Area weight (g/m <sup>2</sup> )	Laminate side Rz (μm)	Tensile Strength (N/mm <sup>2</sup> )	Elongation (%)	Peel Strength (kg/cm)@FR-4
3EC-M2S-VLP	7	65	1.8	500	3	0.5
	9	80	1.8	500	4	0.6
	12	107	1.8	500	5	0.7

※上述列表为代表性数据，非保证数据。

This is representative data, not guaranteed.

处理面/Laminate side



阻剂面/Resist side

